



RELIABILITY REPORT  
FOR  
MAX5544xSA+  
PLASTIC ENCAPSULATED DEVICES

August 19, 2009

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
SUNNYVALE, CA 94086

<b>Approved by</b>
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## Conclusion

The MAX5544xSA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX5544 serial-input, voltage-output, 14-bit monotonic digital-to-analog converter (DAC) operates from a single +5V supply. The DAC output is unbuffered, resulting in low 0.3mA supply current and low 1LSB offset error. The DAC output range is 0V to VREF. The DAC latch accepts a 16-bit serial word. A power-on reset circuit clears the DAC output to 0V (unipolar mode) when power is initially applied. The 10MHz 3-wire serial interface is SPI/QSPI/MICROWIRE compatible and interfaces directly with optocouplers for applications requiring isolation. The MAX5544 is available in an 8-pin SO package.

## II. Manufacturing Information

A. Description/Function:	Low-Cost, +5V, Serial-Input, Voltage-Output, 14-Bit DAC
B. Process:	S12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon, California or Texas
E. Assembly Location:	Philippines, Thailand
F. Date of Initial Production:	October 22, 1999

## III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0401-0495
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	128.4°C/W
M. Multi Layer Theta Jc:	36°C/W

## IV. Die Information

A. Dimensions:	85 X 139 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- |                                   |   |
|-----------------------------------|---|
| A. Quality Assurance Contacts:    | Ken Wendel (Director, Reliability Engineering)<br>Bryan Preeshl (Managing Director of QA)       |
| B. Outgoing Inspection Level:     | 0.1% for all electrical parameters guaranteed by the Datasheet.<br>0.1% For all Visual Defects. |
| C. Observed Outgoing Defect Rate: | < 50 ppm  |
| D. Sampling Plan:                 | Mil-Std-105D  |

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 303 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 3.5 \times 10^{-9}$$
$$\lambda = 3.5 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the S12 Process results in a FIT Rate of 0.09 @ 25C and 1.48 @ 55C, data limited (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The DA58-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-200 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX5544xSA+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	303	0
<b>Moisture Testing</b> (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data